

RoHS
Compliant

Specifications

Dice material	: AlGaInP
Emmiting Colour	: Green
Lens colour	: Water clear
Viewing angle	: 140°
Dominant Wavelength	: 576nm
Luminous Intensity	: 80mcd

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	PD	85	mW
Forward current	If	25	mA
Reverse Voltage	Vr	5	V
Peak Pulsing Current	Ifp	100	mA
Operating Temperature	Top	-40 to +85	°C
Storage Temperature	Tstg.	-40 to +100	°C
Peak Current (1/10Duty Cycle,0.1ms Pulse Width.)	If (peak)	100	mA
Lead Soldering Temperature. (1.6mm from seating plane)	Tsol.	Reflow Soldering : 260°C for 3 sec. Hand Soldering: 350°C for 3 sec.	
Electrostatic Discharge	ESD	2000	V

Electrical and Optical Characteristics

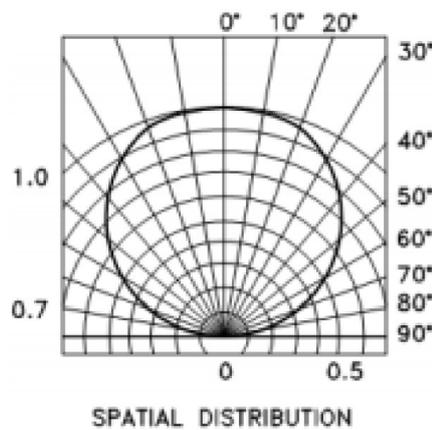
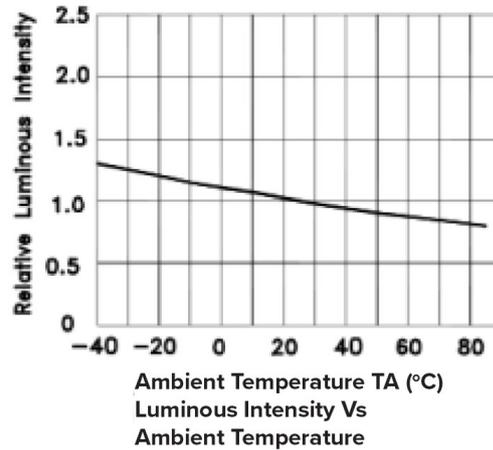
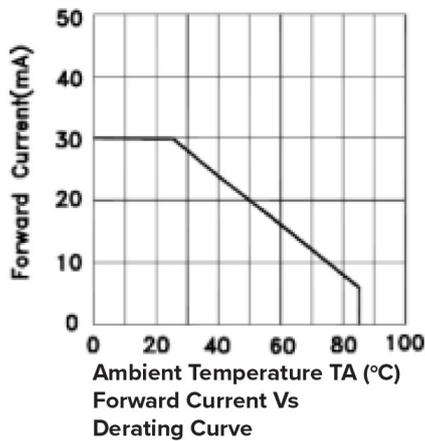
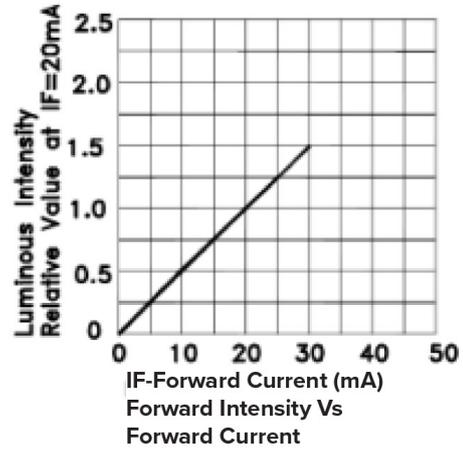
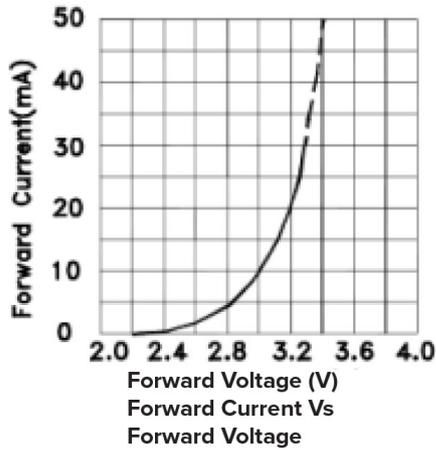
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	Iv	If=20mA	32		80	mcd
Forward Voltage	Vf	If=20mA	1.8		2.4	V
Dominant Wavelength	λd	If=20mA	566		576	nm
Reverse Current	Ir	Vr=5V				μA
Viewing Angle	2θ1/2	If=20mA		140		deg
Spectrum Line Halfwidth	Δλ	If=20mA		15		nm

Notes:

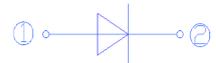
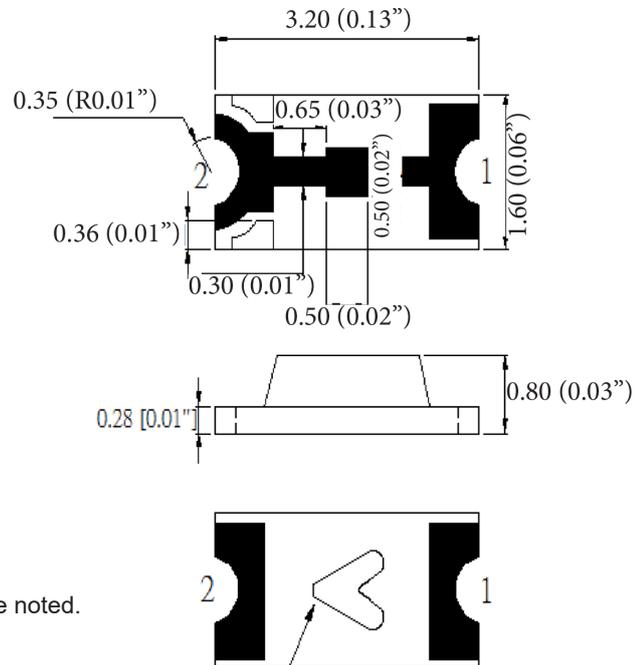
1. Tolerance of Luminous Intensity is ±15%
2. Tolerance of Forward Voltage is ±0.1V
3. Tolerance of Dominant Wavelength is ±1nm

Typical Electrical/Optical Characteristic Curves

(25°C Ambient Temperature Unless Otherwise Noted)



Dimensions



Tolerance is $\pm 0.1\text{mm}$ unless otherwise noted.

Dimensions : Millimetres

Precautions in use:

Storage

It is recommended to store the products in the following conditions:

1. Do not open the moisture proof bag before ready to use the LEDs
2. The LEDs should be kept at 30°C or less and 60%RH or less before opening the package. The max. storage period before opening the package is 1 year.
3. After opening the package, the LEDs should be kept at 30°C/40%RH or less, and it should be used within 7 days
4. If the LEDs are stored contrary to 3, baking is required before mounting.

Baking condition: 60 $\pm 5^\circ\text{C}$ for 24 hours

Hand Soldering

The temperature of the iron should be lower than 300°C and soldering within 3sec per solder-pad is to be observed.

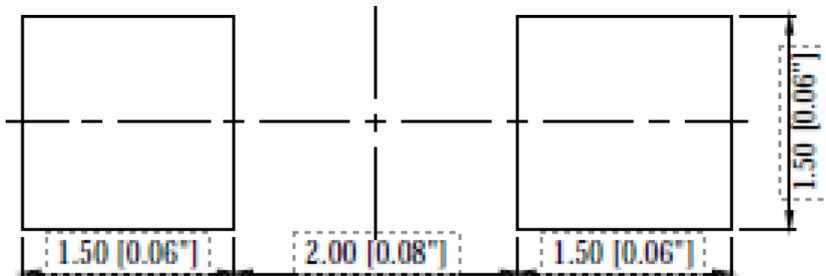
Avoid using organic solvent.

Recommend ultrasonic method 300W Max.

Cleaning

Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

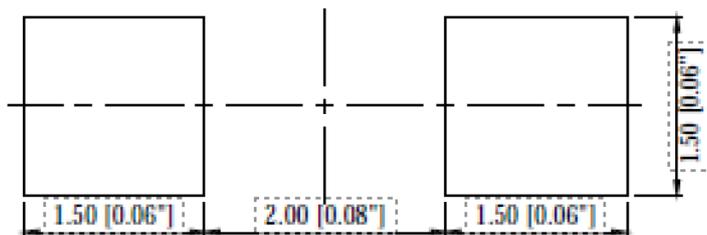
Reflow Temp/Time



Notes:

1. Reflow soldering should not be done more than two times.
2. Do not put stress on the LEDs when soldering.
3. Do not warp the circuit board before it has been returned to normal ambient conditions after soldering.

Reflow Soldering Pad Dimensions



Part Number Table

Description	Part Number
Chip LED, Green, 576nm, 140°, 80mcd, Surface Mount	MP008255

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